Intel® Ethernet Converged Network Adapter X710-DA4

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Specifications

Essentials

Status	Launched
Launch Date	Q4'14
Vertical Segment	Server
Cable Medium	Copper
Cabling Type	SFP+ Direct Attached Twin Axial Cabling up to 10m
Bracket Height	Full Height
Recommended Customer Price	-
Ethernet Controller	Intel® Ethernet Controller XL710-AM1
Product Brief	Link
Conflict Free	Yes

Networking Specifications

# of Ports	Quad
System Interface Type	PCIe v3.0 (8.0 GT/s)
Intel® Virtualization Technology for Connectivity (VT-c)	Yes
Speed & Slot Width	8.0 GT/s, x 8 Lane
Controller	Intel(R) XL710

Package Specifications

Low Halogen Options Available	See MDDS

Intel® Virtualization Technology for Connectivity

On-chip QoS and Traffic Management	Yes
Flexible Port Partitioning	Yes
Virtual Machine Device Queues (VMDq)	Yes
PCI-SIG* SR-IOV Capable	Yes

Advanced Technologies

iWARP/RDMA	No
Intel® Ethernet Power Management	Yes
Intel® Data Direct I/O Technology	Yes
Intelligent Offloads	Yes
Storage Over Ethernet	iSCSI NFS

Related Products

Intel® 10 Gigabit Server Adapters

Intel® Ethernet Converged Network Adapter X710 Series

Products formerly Fortville

CONFLICT FREE

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PCN/MDDS Information

PCN/MDDS Information Not Available

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

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The Recommended Customer -unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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